

PCN# 20210706003.1 Qualification of TI Philippines as an additional Assembly site for select devices Change Notification / Sample Request

Date: July 07, 2021 To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team SC Business Services

20210706003.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP112AIDRLR	null
TMP112AIDRLT	null
TMP302BDRLT	null
TMP102AIDRLR	null
TMP102AIDRLT	null
TMP302BDRLR	null
TMP302CDRLR	null
TMP302CDRLT	null
TMP112BIDRLR	null
TMP302DDRLR	null
TMP112BIDRLT	null

Technical details of this Product Change follow on the next page(s).

PCN Num	ber:	20210706003.1.1 PCN Date: July 07, 202							2021				
Title:	Comparison Compari												
Customer	mer Contact: PCN Manager Dept: Quality Services												
Proposed	1 st Ship Da	te:	Oct 07, 2				-			e Provided at Sample uest			
Change T	ype:												
	nbly Site				Design				Wa	afer Bum	p Site		
	mbly Process			Data Sheet					Wafer Bump Material				
	nbly Materia					umber change				Wafer Bump Process			
	anical Specif			= -	Test Si					Wafer Fab Site			
Packi	ng/Shipping _/	'Labe	ling		Test Pr	rocess		\square	Wafer Fab Materials Wafer Fab Process				
					DON	Datalla			5W	afer Fab	Process		
	on of Chang				PCN	Details							
Additional	ruments Inco Assembly Sit sites and Mat	e for	select de	vice	es listeo	d in the "P							
, 								-					
Accom	bly Site		Assembly Origi		te	Assen	bly Count Code	-			hly Sita (
	ANA		HNT				THA AS			Assembly Site City Ayutthaya			
	CET		JCE			CHN			Jiangyin				
	IPI		PHI				PHL	Baguio City					
Material [Differences:								·	-	<u> </u>		
			ANA		JC	ET	T TIPI						
Mount co	mpound	40	0194	1	120402	001600	4226215						
Mold con	npound	45	0214	1	111020	0003809 4222198							
Reason fo	or Change:												
Continuity	of supply.												
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Anticipated impact on Material Declaration													
🗌 🛛 No I	mpact to the erial Declarat	Material Declarations or Product Content reports are driven from											
Changes t	to product i	dent	ification	res	ulting	from this	s PCN:						

Assembly Site		
HANA	Assembly Site Origin (22L)	ASO: HNT
JCET	Assembly Site Origin (22L)	ASO: JCE
TIPI	Assembly Site Origin (22L)	ASO: PHI

Sample product shipping label (not actual product label)

INSTR	EXAS RUMEN IN: Ma	ITS laysia 20:		P 64		Ĩ
MSL 2 MSL 1	/260C /235C	/1 YEAR /UNLIM	SEAL 03/29	DT /04	14	H.
OPT: ITEM:	E A		39		200) iii
LDL:	JA	(L)T(1:17	00		2

Product Affected:

SN1511004DRLR	TMP102AIDRLT	TMP112BIDRLT	TMP302BDRLR-P
SN1511004DRLT	TMP102BIDRLR	TMP112NAIDRLR	TMP302BDRLT
SN1608035DRLR	TMP102BIDRLT	TMP112NAIDRLT	TMP302CDRLR
SN1710027DRLR	TMP112AIDRLR	TMP302ADRLR	TMP302CDRLT
SN1710027DRLT	TMP112AIDRLT	TMP302ADRLT	TMP302DDRLR
TMP102AIDRLR	TMP112BIDRLR	TMP302BDRLR	TMP302DDRLT

(1P) SN74LS07NSR

(311)LOT: 3959047MLA (4W) TKY(1T) 7523483S12

(2P) REV: (V) 0033317 (20L) CSO:SHE (21L) CCO:USA (22L) ASO:MLA (23L) ACO:MYS

(D) 0336

(a) 2000

(P) (2P) REV:

Qualification Report

Approve Date 17-Jun-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TMP102AIDRLR	Qual Device: <u>TMP112AIDRLR</u>	Qual Device: <u>TMP302ADRLR</u>
PC	PreCon Level 1	MSL1-260C	3/924/0	-	-
HTOL	High Temp Operating Life, 125C	1000 Hours	1/77/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-
TC	Temperature Cycle, -65/150C	1000 Cycles	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	1/77/0	-	-
MSL	Moisture Sensitivity	MSL1-260C	3/36/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0
YLD	Yield Evaluation	(per mfg. Site specification)	Pass	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/pass	-	-

- QBS: Qual By Similarity

- Qual Device TMP112AIDRLR is qualified at LEVEL1-260C

- Qual Device TMP302ADRLR is gualified at LEVEL1-260C

- Qual Device TMP102AIDRLR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle,

Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.